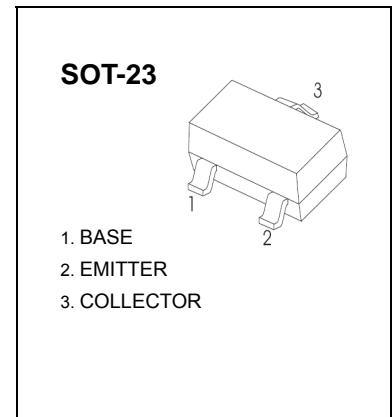


SOT-23 Plastic-Encapsulate Transistors

BAW56/BAV70/BAV99 SWITCHING DIODE

FEATURES

- Fast Switching Speed
- For General Purpose Switching Applications
- High Conductance



BAW56	BAV70	BAV99
MARKING:A1	MARKING:A4	MARKING:A7

Solid dot = Green molding compound device, if none, the normal device

Maximum Ratings @Ta=25°C

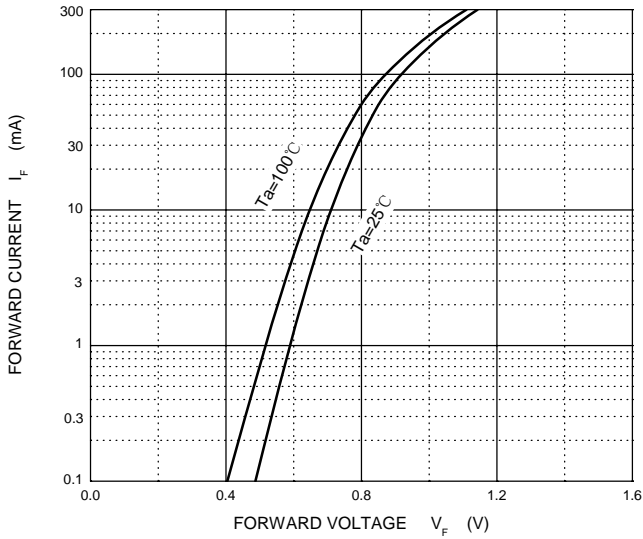
Parameter	Symbol	Limit	Unit
Reverse Voltage	V_R	70	V
Forward Current	I_F	200	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I_{FSM}	2.0	A
Power Dissipation	P_D	225	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	556	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature range	T_{STG}	-55~+150	°C

Electrical Characteristics @Ta=25°C

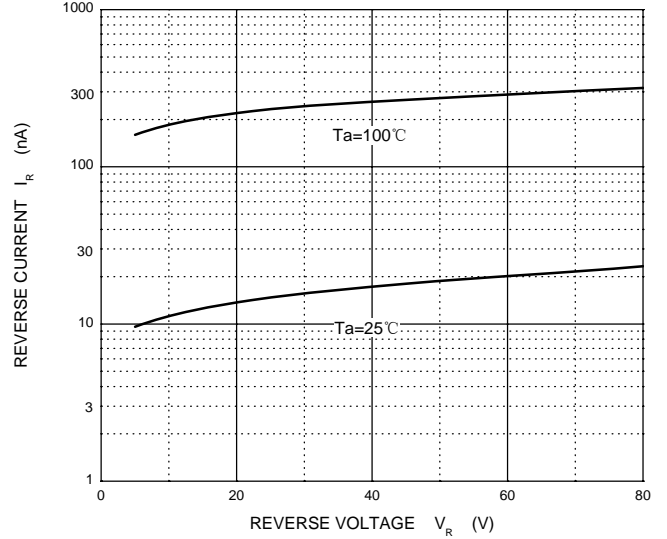
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse breakdown voltage	V_R	70			V	$I_R=100\mu A$
Forward voltage	V_{F1}			0.715	V	$I_F=1mA$
	V_{F2}			0.855	V	$I_F=10mA$
	V_{F3}			1	V	$I_F=50mA$
	V_{F4}			1.25	V	$I_F=150mA$
Reverse current	I_R			2.5	μA	$V_R=70V$
Capacitance between terminals	C_T			1.5	pF	$V_R=0, f=1MHz$
Reverse recovery time	t_{rr}			6	ns	$I_F = I_R = 10mA,$ $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Typical Characteristics

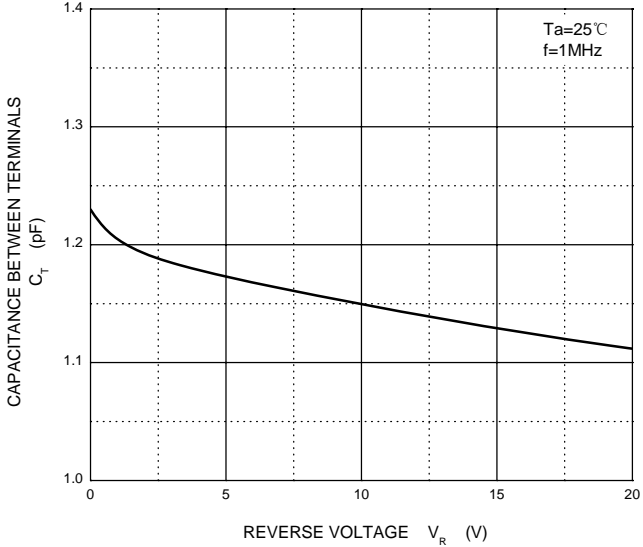
Forward Characteristics



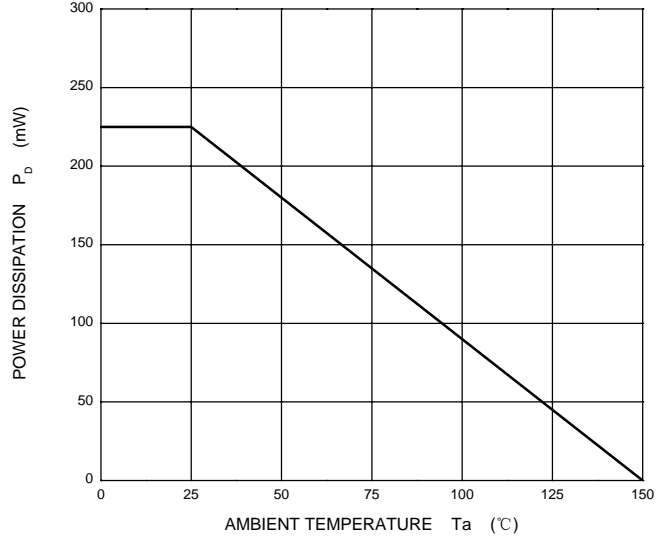
Reverse Characteristics



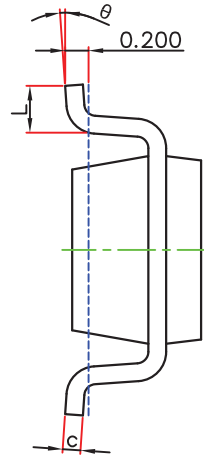
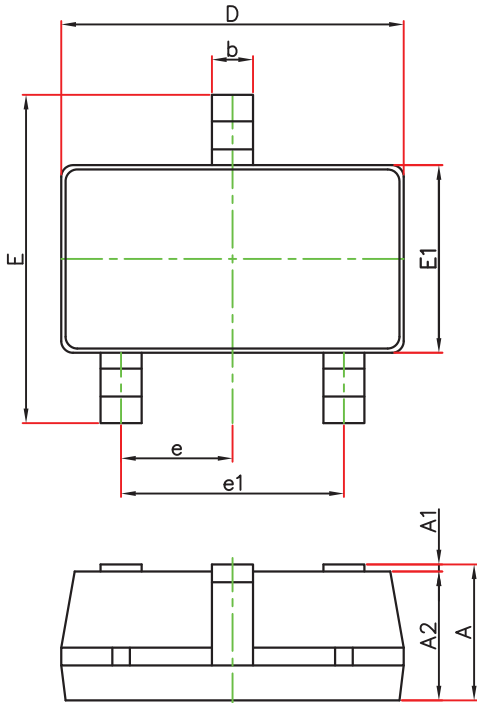
Capacitance Characteristics



Power Derating Curve



SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°